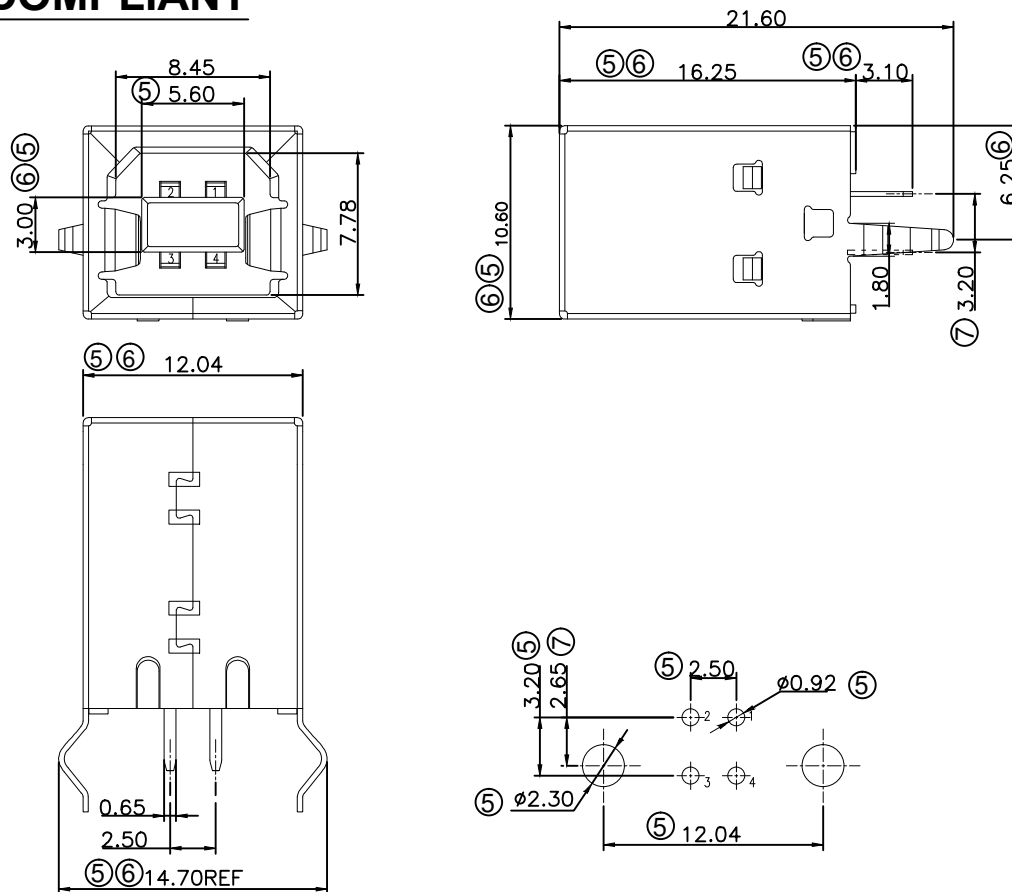


USB 2.0 COMPLIANT



- NOTES:
- ⑤ 1. MATERIAL:
 - 1.1 Housing: PBT+30%GF UL94V-0, Color White
 - 1.2 Contact : Brass
 - 1.3 Shell: Brass
 - 2. FINISH:
 - 2.1 Contact:
 - Contact Area: Selective gold flash
 - Solder Area: Tin Plated
 - Under Plate: Ni Plated
 - 2.2 Shell: Ni Plated
 - 3. MECHANICAL:
 - 3.1 Mating Force: 3.5 kgf MAX
 - 3.2 Unmating Force: 1.0 kgf MIN
 - 3.3 Durability: 1500 Cycles MIN
 - 4. ELECTRICAL:
 - 4.1 Current Rating: 1.0A
 - 4.2 Dielectric Withstanding Voltage: 500V AC
 - 4.3 Contact Resistance: 30mΩ MAX
 - 4.4 Insulation Resistance: 1000MΩ MIN
 - 5. OPERATING TEMPERATURE: -55°C To +85°C.
 - 6. ENVIRONMENTAL:
 - Recommended PC Board Thickness: 1.6±0.05mm
 - Packing: Tray

RoHS compliant
Unit: mm

Scale	Free	⑦	Update dimension&Shell	30.07.2019	Winnie		Date	Name	Customer-No.
TOLERANCE		⑥	Update dimension	30.07.2019	Xavier	Drawn	25.03.2006	Hellwig	ASSMANN WSW-No. A-USB B-TOP-C
.X	±0.30	⑤	Update	24.05.2018	Segal	Approved	15.10.2018	Winnie	
.XX	±0.20	④	Add soldering temperature	15.09.2014	Amy				
.XXX	±0.10	③	Add "USB 2.0 COMPLIANT"	19.08.2013	Amy				Drawing-No.
DIM	TOL	③							ASS 1370C CO rev07
X.°	±5°	②	Update	07.07.2009	Dean				
.X°	±3°								SHEET 1/1
Angle	TOL	Id.	Modification	Date	Name				



Customer-No.	
ASSMANN WSW-No. A-USB B-TOP-C	
Drawing-No.	rev07
Replace	SHEET 1/1